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REMARKS/ARGUMENTS

Claims 1-3 are pending in this application. By this Amendment, Applicants AMEND claim 1.

Claims 1-3 were rejected under 35 U.S.C. § 103(a) as being unpatentable over Brebels et al. (U.S. 5,675,295) in view of Kornrumpf et al. (U.S. 5,355,102), further in view of Carey et al. (U.S. 5,219,787), further in view of Ohya et al. (U.S. 5,686,172), and further in view of at least one of: Trinh et al. (U.S. 5,132,648), Peterson (U.S. 5,574,415), and/or Kroger (U.S. 4,490,733). Applicants respectfully traverse the rejection of claims 1-3.

Claim 1 has been amended to recite:

"A method of producing a thin film circuit board used as a milli-wave or micro-wave module, the method comprising steps of:

cleaning a substrate comprising dielectric ceramic, and having a thickness of 0.05 mm to 2 mm and a flexural strength of 500 kgf/cm² to 4000 kgf/cm²;

forming a conductor film in a predetermined pattern on the substrate, said conductor film including at least one selected from Cu, Au, Ag, Al, Ni, Ti, Cr, Ni-Cr, Nb, and V;

forming an insulating film on the substrate to cover the entire conductor film, said insulating film comprising at least one organic resin selected from polyimide, epoxy resins, benzocyclobutene resins, acrylic resins, and cyclic olefin resins, and having a thickness of 20 µm or greater, an area of 5 cm² or less per pattern, and a stress of 15 MPa to 60 MPa;

patterning the insulating film; and

repeating the insulating film forming step and the insulating film patterning step more than once." (emphasis added)

Applicants' claim 1 recites the steps of "forming an insulating film on the substrate to cover the entire conductor film," "patterning the insulating film" and "repeating the insulating film forming step and the insulating film patterning step more than once." With the improved features of claim 1, Applicants have been able to provide an improved method of producing a thin film circuit board even when an insulating film comprising an organic resin is thickened (see, for example, the paragraph

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bridging pages 3 and 4 of the Specification).

The Examiner has again maintained the allegation that Brebels et al. teaches the step of "repeating the insulating film forming step and the insulating film patterning step more than once." Although Applicants strongly disagree with the Examiner's allegation, in order to expedite and advance prosecution of the present application, Applicants have amended claim 1 to recite the feature of "forming an insulating film on the substrate to cover the entire conductor film."

The Examiner alleged that col. 19, lines 26-22-44 Brebels et al. teaches a low dielectric loss material, which the Examiner alleged corresponds to the insulating film recited in Applicants' claim 1. However, as clearly seen in Figs. 17A-20C of Brebels et al., the low dielectric loss material 81 covers only a portion of the conductor film 86, and the low dielectric loss material 85 disposed on the lower surface of the substrate 80 is not patterned. Thus, Brebels et al. fails to teach or suggest the steps of "forming an insulating film on the substrate to cover the entire conductor film" and "patterning the insulating film" as recited in Applicants' claim 1.

The Examiner has relied upon Kornrumpf et al., Carey et al., Ohya et al., Trinh et al., Peterson, and Kroger to allegedly cure various deficiencies in Brebels et al. However, none of Kornrumpf et al., Carey et al., Ohya et al., Trinh et al., Peterson, and Kroger teach or suggest the steps of "forming an insulating film on the substrate to cover the entire conductor film" and "patterning the insulating film" as recited in Applicants' claim 1.

Accordingly, Applicants respectfully submit that Brebels et al., Kornrumpf et al., Carey et al., Ohya et al., Trinh et al., Peterson, and Kroger, applied alone or in combination, fail to teach or suggest the unique combination and arrangement of elements recited in claim 1 of the present application. Claims 2 and 3 depend upon claim 1 and are therefore allowable for at least the reasons that claim 1 is allowable.

In view of the foregoing amendments and remarks, Applicants respectfully submit that this application is in condition for allowance. Favorable consideration and prompt

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allowance are solicited.

The Commissioner is authorized to charge any shortage in fees due in connection with the filing of this paper, including extension of time fees, to Deposit Account No. 50-1353.

Respectfully submitted,

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